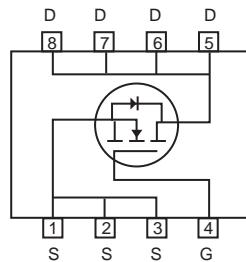
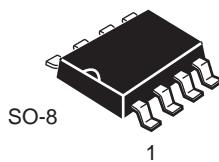


N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 30V ,12.5A, $R_{DS(ON)} = 10m\Omega$ @ $V_{GS} = 10V$.
 $R_{DS(ON)} = 13.5m\Omega$ @ $V_{GS} = 4.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	12.5	A
Drain Current-Pulsed ^a	I_{DM}	50	A
Maximum Power Dissipation	P_D	2.5	W
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	50	$^\circ C/W$



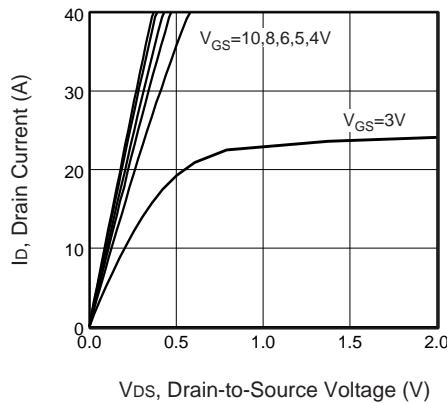
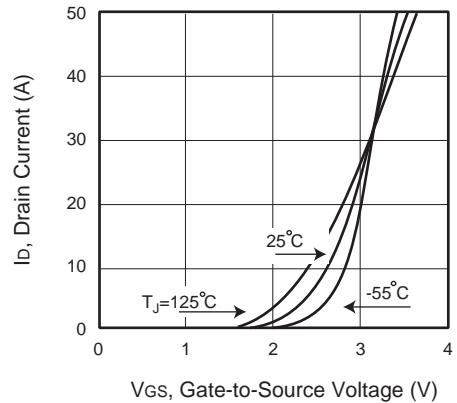
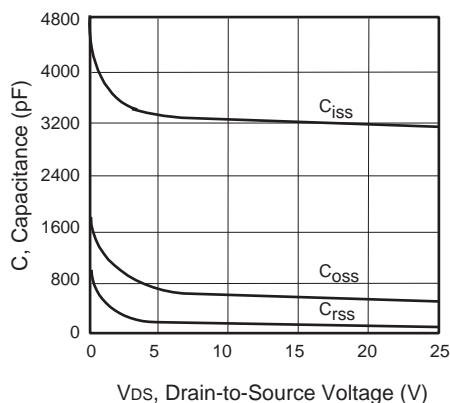
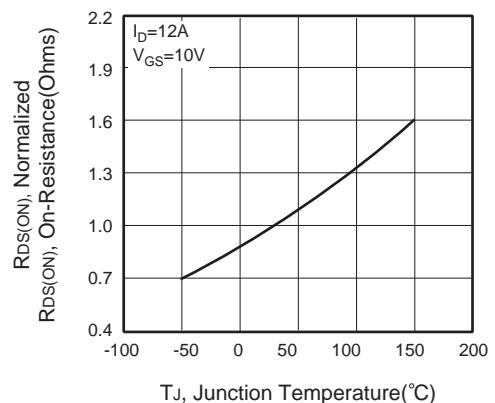
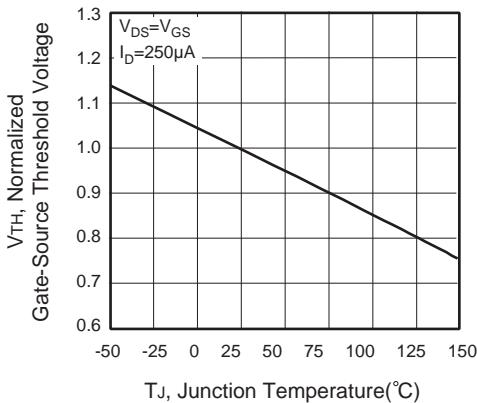
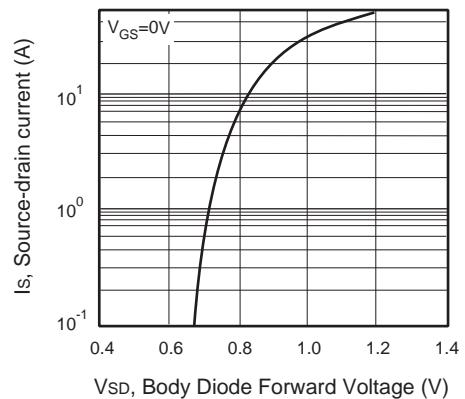
CEM8811

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^c						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 12\text{A}$		8	10	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 15\text{V}, I_D = 12\text{A}$		11	13.5	$\text{m}\Omega$
Dynamic Characteristics^d						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3288		pF
Output Capacitance	C_{oss}			582		pF
Reverse Transfer Capacitance	C_{rss}			224		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		18	35	ns
Turn-On Rise Time	t_r			9	16	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			73	135	ns
Turn-On Fall Time	t_f			15	30	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_D = 12\text{A}, V_{\text{GS}} = 5\text{V}$		28.7	37.3	nC
Gate-Source Charge	Q_{gs}			8.5		nC
Gate-Drain Charge	Q_{gd}			8.7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				2.3	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 2.3\text{A}$			1.1	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board, $t \leq 10$ sec.
- c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- d.Guaranteed by design, not subject to production testing.

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

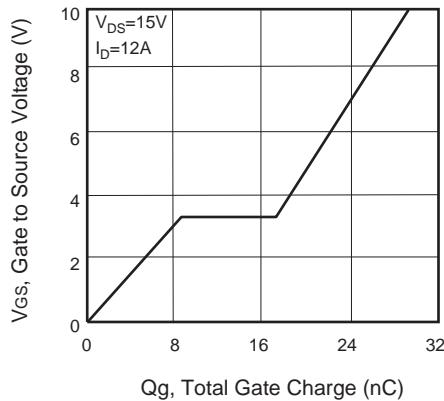


Figure 7. Gate Charge

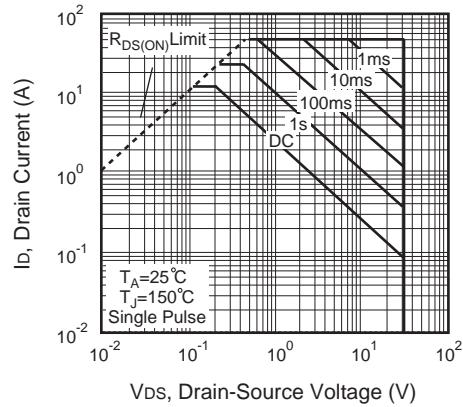


Figure 8. Maximum Safe Operating Area

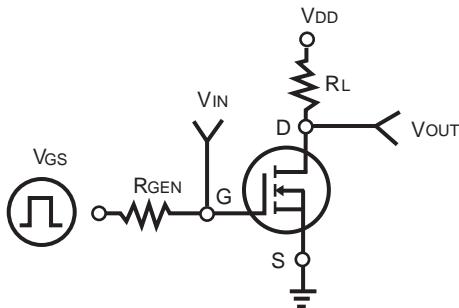


Figure 9. Switching Test Circuit

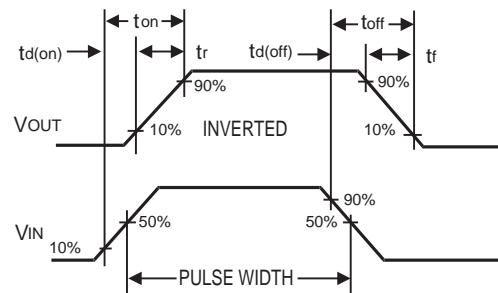


Figure 10. Switching Waveforms

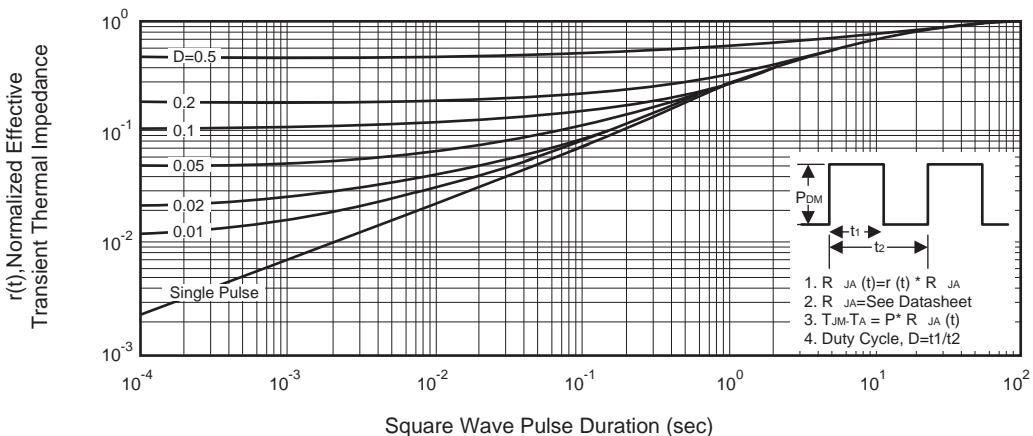


Figure 11. Normalized Thermal Transient Impedance Curve